Bondable Products

Magnet Wire / Winding Wire

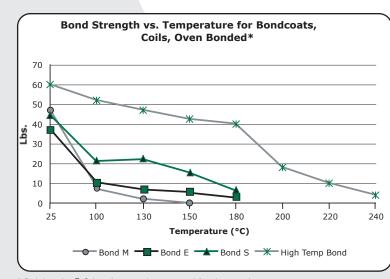
BONDABLE PRODUCTS AND BONDING GUIDELINES

Bondable magnet wire products are described by the basecoat and topcoat materials. Polybondex[®] describes a number of possible constructions of bondable wire having a GP/MR-200[®] or Thermalex 200[®] base insulation with a thermoplastic bondcoat. For example, Polybondex[®] T indicates that the basecoat is Thermalex 200[®]. Polybondex[®] G indicates that the basecoat is GP/MR-200[®]. The bondcoat is designated by the letters M (Epoxy), S (Aromatic Polyamide), or E (Polyester).

Bondable Product	Metal	Basecoat Polymer	Topcoat Polymer	Bondcoat Polymer	Temperature Rating (°C)	Bonding Temperature Guidelines (°C)	NEMA MW 102
Polybondex [®] G, Bond M	AL/CU	Polyester	Polyamide-imide	Ероху	180	150-200	
Polybondex® G, Bond S	AL/CU	Polyester	Polyamide-imide	Aromatic Polyamide	180	210-230	х
Polybondex [®] G, Bond E	AL/CU	Polyester	Polyamide-imide	Polyester	180	180-200	х
Polybondex [®] T, Bond M	AL/CU	Polyester	N/A	Ероху	180	150-200	
Polybondex [®] T, Bond S	AL/CU	Polyester	N/A	Aromatic Polyamide	180	210-230	
Polybondex® T, Bond E	AL/CU	Polyester	N/A	Polyester	180	210-230	
Soderbond [®] N/155	CU	Polyurethane	Nylon	Butvar	155	110-150	
Amide-Imide High Temp Bond	CU	Amide-Imide	N/A	Proprietary	N/A	275-300	
Amide-Imide Bond S	CU	Amide-Imide	-	Aromatic Polyamide	-	210-230	

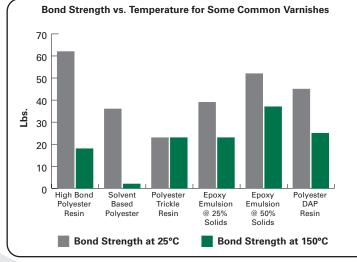
Note: The information provided in this chart is provided for convenience only and is not intended to be a complete product listing. Please consult Magnet Wire Marketing for additional constructions and product information. The bond strength and melt temperatures required will define the proper bondcoat to use.

BOND STRENGTH COMPARISIONS



* Polybondex ${}^{\textcircled{R}}$ G bond strength was used for the graph.

Note: Helical coil bond strength, NEMA MW 1000-2008.



Note: Helical coil bond strength per ASTM D2519.

BONDCOAT COMPARISONS

BONDCOAT TYPE	BONDING METHODS	
Bond M	 Solvent - Methylethyl ketone Heat bonding is recommended 	• Use at to exc 130°C
Bond S	• Heat activated	 Aroma High b elevate
Bond E	• Heat activated	• Requir to effe
Soderbond® N/155	Denatured or isopropyl alcoholHeat activated	• High te tions v insulat
High Temp Bond	• Heat activated	 Proprin High b elevate

THREE COMMON TYPES OF BONDING

SOLVENT BONDING

Some bondcoats can be activated by the application of certain solvents during or after coil winding. The solvent may be applied to the wire via a wick during the winding operation or the finished coils may be dipped in a bath of solvent after winding. In either case, the unit should be heated again to drive off residual solvent and to complete the bonding of the coils.

HEAT – OVEN BONDING

After the coils are formed, the unit is heated in an oven which causes the bondcoat to flow and bond the adjacent turns of wire together.

HEAT – RESISTANCE BONDING

Resistance heating is similar to oven heating, except that passing current through the formed coils supplies the heat. Time, voltage, and current are all unique to each application.

Essex Furukawa 1601 Wall Street Fort Wayne, IN 46802 260.461.4000 © 04-2023 Essex Furukawa

Bondable Products

Magnet Wire / Winding Wire

PRODUCT DATA SHEET

FEATURES APPLICATIONS Armatures Transformers temperatures not Motor stators Transponders eed approximately Sensors • Various coil Small motors applications atic polyamide Appliance motors • Sensors Lift magnets Small motors bond strength at Motor stators Solenoids ted temperatures • Appliance motors • Sensors res minimal energy High temperature • Solenoids ectively bond • Transformers motors temperature applica- • Solenoids where a solderable Helical coils Toroidal coils tion is desired ietary polymer Suitable for applications requiring bond strength at high thermal properties ted temperatures

FILM BUILDS ON BONDABLE WIRE

The addition of the bondcoat adds one overall build level to the wire dimension.

#0: Overall single build; half basecoat and half bondcoat - This film may not be a recommended choice for all AWG sizes. Please consult Essex Furukawa Magnet Wire Marketing for size availability.

#1: Overall heavy build; single build film insulation plus single build bondcoat.

#2: Overall triple build; heavy build film insulation plus single build bondcoat.

Note: Since the bondcoat will be softened and displaced during bonding, it should be stressed that the bondcoat will not contribute to the electrical integrity of the film coating on the wire. The basecoat alone will determine the electrical properties of the wire.

In addition, product engineering should be aware of the additional space requirements necessary due to the additional build of the bondcoat. The turns density of the coil will be adversely affected with the addition of a bondcoat.

NEMA MW 102-C*

APPLICATION

Bondable magnet wire products are an excellent choice for applications requiring the magnet wire to be a compact, self-supporting coil. Bondable wire consists of standard magnet wire insulations overcoated with a thermo-plastic polymer that can be temporarily softened by either heat or solvent, or both. The use of bondable magnet wire allows the coil to be self-supporting so that bobbins or additional varnishing is not necessary. Bondable magnet wire can also assist in reducing the work in progress and shortening the product assembly time; which can help lead to more efficient winding operations.

Depending on the desired application, bondable magnet wire products offer a wide variety of bondcoat polymers and different bond strengths, along with excellent thermal properties and chemical resistance.

Bondable products are typically used, but not limited to the following applications:

- Armatures
- Bobbinless coils
- Clutch coils
- Ignition coils Lift magnets
- Transformers

Relays

Sensors

Solenoids

Stators

Motors

*Not applicable to all bondcoats.

ENGINEERING HIGHLIGHTS

1. THERMAL CLASSIFICATION

Essex Furukawa offers bondable products that can have a rating above and below an 180°C thermal class rating. Typical heat shock resistance passes 220°C with no cracks.

2. THERMOPLASTIC FLOW

Bondable magnet wire products have excellent thermoplastic flow (cut-thru) properties. Typical test values well exceed the 300°C requirement.

3. WINDABILITY

The flexiblity and adhesion properties of bondable products are excellent and suitable for most winding applications.

4. ELECTRICAL

Bondable products exhibit high dielectric strength.

5. NORMAL AVAILABILITY

Please consult Essex Furukawa Magnet Wire Marketing for size (including metric) and build information.



Bondable Products

Magnet Wire / Winding Wire

1B Polybancker'T # E Bond S Typical Parlomance Tupical Parlomance 1B Polybancker'T # E Bond S Typical Parlomance Tupical Par			
PHYSICAL PROPERTIES r	18 Polybonde	18 Polybondex® G #2 Bond M	
EONDUCTOR ELONGATION 38% 32%, minimum 54% 62°, maximum 64% 62°, maximum	nce [†] Typical Performance	Required Performance	
SPRINEBACK 54* 62*, maximum 62*, m			
FlexibilitY Pass 20%, 3X0, No exposed bare Pass Xo Requirement Established 103 exp, strictes No Requirement Established 0.206 No Requirement Established .0206 No Requirement Esta	38%	32%, minimum	
ABRASION RESISTANCE: REPEATED SCRAPE 42 avg. strokes No Requirement Established 109 avg. strokes No Requirement Established 120 avg. strokes No Requirement Established 130 avg. strokes No Requirement Established 120 avg. strokes No Requirement Established 130 avg. strokes No Requirement Established ABRASION RESISTANCE: UNILATERAL SCRAPE 2448 Actual Performance 2513 Actual Performance 2700 Actual Performance 3105 Actual Performance 2700 Actual Performance 3105 Actual Performance 2700 Actual Performance 3105 Actual Performance 2700 Actual Performance 2700 Actual Performance 3105 Actual Performance 2700 Actual Perf	54°	62°, maximum	
ABRASION RESISTANCE: UNILATERAL SCRAPE 2448 Actual Performance 3000 Actual Performance 2513 Actual Performance 2700 Actual Performance 3195 Actual Performance 2568 Avg. Performance 3145 Avg. Performance 2563 Avg. Performance 2700 Actual Performance 3240 Avg. Performance CDEFFICIENT OF FRICTION 0.2 - 06 No Requirement Established 0.2 - 06 No Requirement Established <td>bare Pass</td> <td>20%, 3XD, No exposed bare</td>	bare Pass	20%, 3XD, No exposed bare	
cdc2568Arg. Performance3145Arg. Performance2563Arg. Performance2760Arg. Performance3240Arg. PerformanceC0EFICIENT 0F FRICTION.02 · .06No Requirement Established.02 · .06No Requirement EstablishedNo Req	ished 99 avg. strokes	No Requirement Established	
COEFFICIENT OF FRICTION 0206 No Requirement Established .0206 No Requirement Established	e 2100	Actual Performance	
CHEMICAL PROPERTIES No No <td>2175</td> <td>Avg. Performance</td>	2175	Avg. Performance	
SOLUBILITY (Xylene) Pass Xylene, No exposed bare Pass Xylene/butyl cellosolve, No exposed bare Pass Zylene/butyl cellosolve, No exposed bare Pass Zylene/butyl cellosolve, No exposed bare No exposed bare	ished .0206	No Requirement Established	
SOLUBILITY (Xylene/Butyl) Pass Xylene/butyl cellosolve, No exposed bare Pass Zufw, 3XD @ 200°			
No exposed bareNo exposed ba	pare Pass	Xylene, No exposed bare	
THERMAL PROPERTIES HEAT SHOCK RESISTANCE Pass 20%, 3XD @ 200° No exposed bare	ve, Pass	Xylene/butyl cellosolve,	
HEAT SHOCK RESISTANCE Pass 20%, 3XD @ 200° No exposed bare Pass 20%, 3XD @ 200° Pass 20%, 3XD @ 200° Pass 20%, 3XD @ 200° Pass 20% offer and		No exposed bare	
No exposed bareNo exposed ba			
THERMOPLASTIC FLOW> 350°CMedian min. 300°C> 350°CMedian min. 300°C> 350°CMedian min. 300°C> 375°CMedian min.	Pass	20%, 3XD @ 200°	
ELECTRICAL PROPERTIES Image: Construct of the state of the stat		No exposed bare	
DIELECTRIC BREAKDOWN VOLTAGE ROOM TEMPERATURE 12,200 volts, avg. 5,700 volts, minimum	> 375°C	Median min. 300°C	
R00M TEMPERATURE 12,200 volts, avg. 5,700 volts, minimum 12,200 volts, avg. 5,700 volts, minimum 12,200 volts, avg. 5,700 volts, minimum DELECTRIC BREAKDOWN VOLTAGE RATED TEMPERATURE			
DIELECTRIC BREAKDOWN VOLTAGE RATED TEMPERATURE Augustic avg. 4,275 volts, minimum 10,300 volts, avg. 4,275 volts, minimum 10,300 volts, avg. 4,275 volts, minimum CONTINUITY @ 1,500 VOLTS ≤ 1 faults/100 ft. 5 faults/100 ft.			
RATED TEMPERATURE 10,300 volts, avg. 4,275 volts, minimum 10,300 volts, avg. 4,275 volts, minimum 10,300 volts, avg. 4,275 volts, minimum CONTINUITY@1,500 VOLTS ≤ 1 faults/100 ft. 5 faults/100 ft.<	m 12,200 volts, avg.	5,700 volts, minimum	
CONTINUITY @ 1,500 VOLTS $\leq 1 \text{ faults/100 ft.}$ $5 faul$			
BOND STRENGTH @ ROOM TEMPERATURE 34.35 No specification 30.38 No specification 45.41 30 lbs min. 38.49 30 lbs m		4,275 volts, minimum	
	≤ 1 faults/100 ft.	5 faults/100 ft.	
Bond M and E Bonded @ 200°C - 1 hour	47.00	No specification	
Bond S Bonded @ 220°C - 1 hour	0.70	Ne en esitie etien	
BOND STRENGTH @ 100°C 27.79 No specification 11.95 No specification 24.31 No specification 10.57 No specification 0.50 No specificat	8.78	No specification	
BOND STRENGTH @ 130°C 25.42 No specification 9.58 No specification 3.30 No specification 22.05 No specification 8.46 No specification 7.47	2.18	No specification	
BOND STRENGTH @ 150°C 20.78 No specification 7.47 No specification No specification 7.14	No Bond Strength	No specification	
BOND STRENGTH @ 180°C 6.51 No specification - - 7.37 3 lbs min. [†] 4.24 3 lbs min. [†]	•	-	

Note: The values shown represent typical average results and are not intended to be used as design data or specification limits. † Requirements of NEMA MW 1000; Section MW 102. Typical performance of base coat.

For customized or engineered bondable constructions, please consult Essex Furukawa Magnet Wire Marketing.

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